

User's Guide

NHD-2.4-240320YF-CTXI#-T-1 **TFT**

(Liquid Crystal Display Graphic Module)

2.4" Diagonal16-bit digital interface240x320 Resolution (portrait mode)White LED BacklightWith Touch Panel

Please review the controller spec HX8347.

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RECORDS OF REVISION

DATE	REVISED NO.	REVISED DESCRIPTIONS	PREPARED	CHECKED	APPROVED
Aug-10-2007	1.00	FIRST ISSUE			
Jul-1-2008	2.0	Change controller from ILI9320 to HX8347			

CONTENTS

1.	FEATURES	1
2.	BLOCK DIAGRAM &APPLICATION CIRCUIT	1
3.	OUTLINE DIMENSIONS	2
4.	INTERFACE PIN CONNECTIONS	4
5.	ELECTRICAL CHARACTERISTICS	4
6.	Electro-Optical Characteristics	5
7.	QUALITY GUARANTEE & INSPECTION CRITERIA	8
8.	RELIABILITY	11

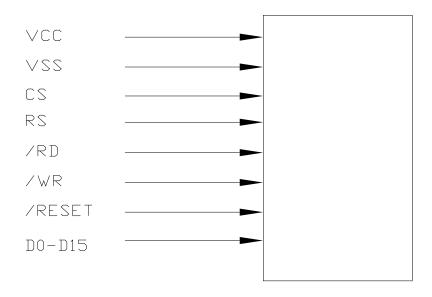
1. FEATURES

ITEM	STANDARD VALUE	UNIT
LCD Type	2.4" QGVA TFT-LCD (Thin Film Transistor Liquid Crystal Display)	
Viewing Direction	6:00	O'clock
Backlight Type	4-parallel-White LED	
Module Outsize	42.72*60.26*3 thickness=3.8 (with TP)	mm
TP Viewing area	38.72*54.36	mm
TP Active area	37.72*53.36	mm
LCD Active area	36.72*48.96	mm
Dot Number	240(RGB) × 320	
Dot size	0.153*0.153	mm
Operation temperature	-10 ~70	${\mathfrak C}$
Storage temperature	-30 ~80	${\mathfrak C}$
Driver IC	HX8347	
Interface mode	8080 System 16 bit Interface	

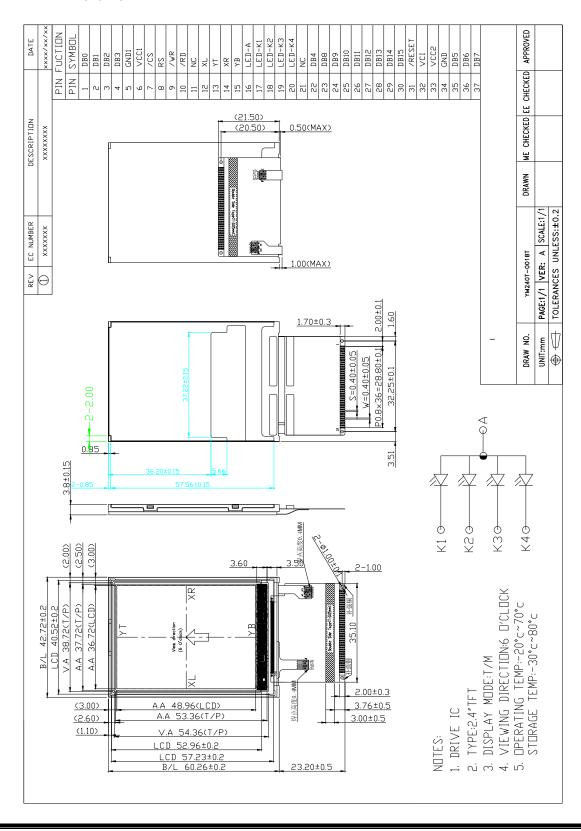
Remark:

1. Display color support 262K/65K, In detail please see also the HX8347 specification.

2. BLOCK DIAGRAM



3. OUTLINE DIMENSIONS



4. INTERFACE PIN CONNECTIONS

PIN	SYMBOL	FUNCTION
1	DB0	
2	DB1	
3	DB2	Data bus
4	DB3	
5	GND	Ground
6	VCC	Power supply
7	/CS	Chip select input pin ("Low" enable).
8	RS	Display data / Command selection pin
9	/WR	Write pin
10	/RD	Read pin
11	NC	No Connect
12	XL	Left electrode
13	YT	Top electrode
14	XR	Right electrode
15	YB	Bottom electrode
16	LED-A	Backlight power supply
17	LED-K1	
18	LED-K2	
19	LED-K3	Backlight ground
20	LED-K4	
21	NC	NO connect
22	DB4	
23	DB8	
24	DB9	
25	DB10	
26	DB11	Data bus
27	DB12	
28	DB13	
29	DB14	
30	DB15	
31	/RESET	Reset pin
32	VCC	Power supply
33	VCC	
34	GND	Ground
35	DB5	
36	DB6	Data bus
37	DB7	

5. ELECTRICAL CHARACTERISTICS

5.1 ABSOLUTE MAXIMUM RATING

Please Refer to the SPEC of HX8347.

Version 2

6. Electro-Optical Characteristics

6.1 Backlight Unit

Item	Symbol	Min	Тур.	Max	Unit	Remark	
Input voltage	V_{BL}		3.2		V	-	
Current	I_{BL}		18		mA/chip	-	
ICE	X	0.26	-	0.30	-	V>V	
ICE	Y	0.27	-	0.31	-	X>Y	
Brightness	-		3200		cd/m²		
Luminous Intensity Ratio	-			20	%	-	

6.2 LCD panel

Item		Cumbal	Conditions	Specifications			Limit	Note
		Symbol	Conditions	Min.	Тур.	Max.	Unit	Note
Transmittance	Transmittance				4.7		%	
Contrast Ratio	Contrast Ratio			150	250	-	-	
Bosponso Tin	20	T_R		NA	10	20	ms	All left side data
Response Tin	ile	T _F		NA	20	30	ms	are based on
	Red	X_R		0.603	0.633	0.663		CMO's following
	Red	Y _R	Viewing normal angle	0.299	0.329	0.359		condition – Type 767 NTSC: 60%
	Green	X_{G}		0.264	0.294	0.324		
Chromoticity		Y_{G}		0.546	0.576	0.606		
Chromaticity	Blue	X _B		0.103	0.133	0.163		LC:5066 Light : C light
		Y _B		0.092	0.122	0.152		(Machine:BM5A)
	White	X _W		0.278	0.308	0.338		Normal Polarizer
		Yw		0.316	0.346	0.376		Without DBEF
Viewing Angle	HOI.	θ_{X^+}			45	-		
		θ _X .	Center		45	-	doa	
	Ver θ_{Y}	θ_{Y^+}	CR≥10		35	-	deg.	
		θ _{Υ-}			15	-		

*Note (1) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

Contrast Ratio (CR) = L63 / L0

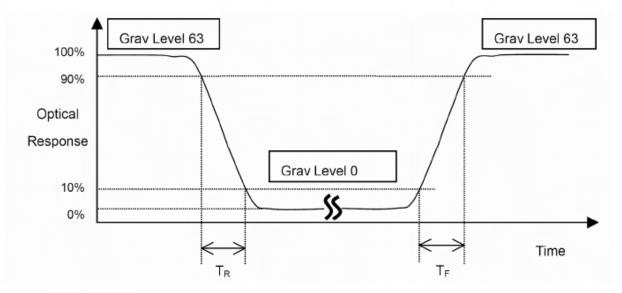
L63: Luminance of gray level 63

L0: Luminance of gray level 0

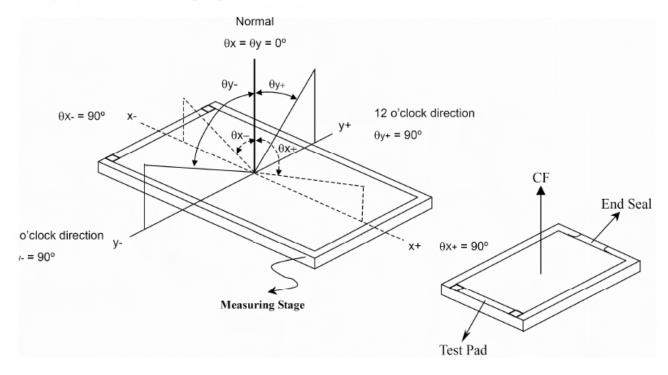
CR = CR(10)

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (6).

*Note (2) Definition of Response Time (TR, TF):

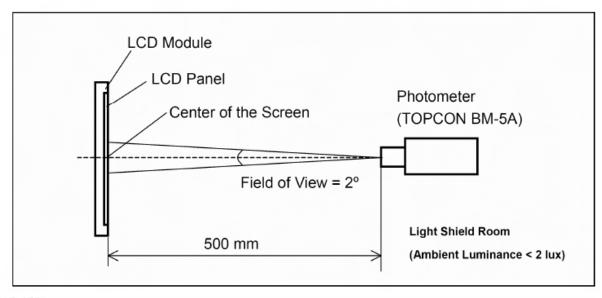


*Note(3) Definition of Viewing Angle

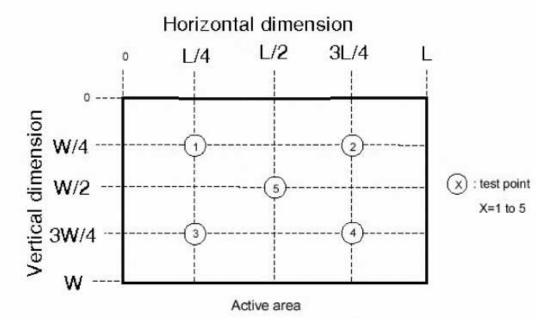


*Note (4) Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.





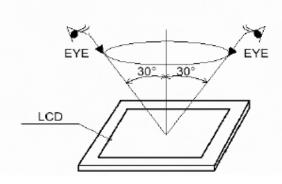


7. QUALITY GUARANTEE & INSPECTION CRITERIA

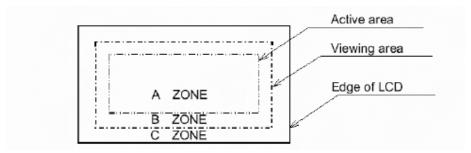
7.1 Appearance inspection

Appearance inspection should be done under the following condition.

- (1) In the dark room.
- (2) The distance from eyes to LCD must be 30 cm.
- (3) Viewing direction must be within 30 degrees to vertical line of LCD center.



7.2 Definition of A zone, B zone and C zone



7.3 Electrical Testing

- 1. Missing vertical, horizontal segment, segment contrast defect.
- 2. Missing character, dot or icon.
- 3. Display malfunction.
- 4. No function or no display.
- 5. Current consumption exceeds product specifications.
- 6. LCD viewing angle defect.
- 7. Mixed product types.
- 8. Contrast defect

7.4 Black or white spots on LCD (display only)

- 1. White and black spots on display ≤ 0.20 mm, no more than three white or black spots present.
- 2. Densely spaced: No more than two spots or lines within 5mm

7.5 LCD black spots, white spots, contamination (non-display)

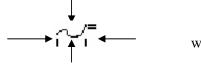
1. Round type: As following drawing

$$\Psi = (x+y)/2$$

$$Y$$

SIZE	Acceptable QTY
ψ≤0.10	Accept no dense
0.10 ⟨ψ≤0.15	2
0.15 ⟨ψ≤0.20	1
total	2

2. Line Type: (As following drawing)



Т

Length	Width	Acceptable QTY
	$W \leq 0.02$	Accept no dense
L≦3.0	$0.02 < W \le 0.03$	
L≦2.5	$0.03 < W \le 0.05$	2
	0.05< W	As round type

7.6 Polarizer bubbles

If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.

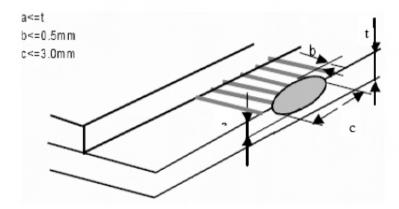
Size Ψ	Acceptable QTY
Ψ ≤ 0.20	Accept no dense
0.20< Ψ ≤ 0.50	2

7.7 Chipped glass

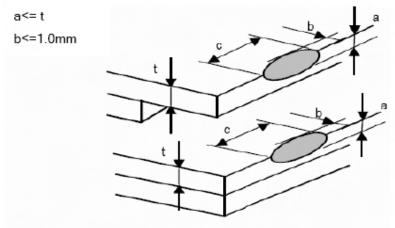
Symbols:

- a: Chip length b: Chip width c: Chip thickness
- t: Glass thickness

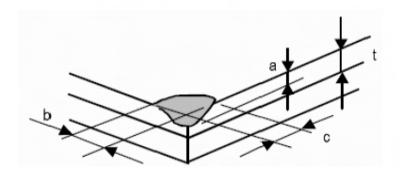
1 ITO electrode



2 General, corner portion



*Effective width of seal area shall be more than 0.3mm.



7.8 Backlight elements

- 1. Illumination source flickers when lit.
- 2. Spots or scratches that appear when lit must be judged using LCD spot, lines and contamination standards.
- 3. Backlight doesn't light or color is wrong

7.9 Soldering

- 1. No unmelted solder paste may be present on the PCB.
- 2. No cold solder joints, missing solder connections, oxidation or icicle.
- 3. No residue or solder balls on PCB.
- 4. No short circuits in components on PCB.

7.10 General appearance

- 1. No oxidation, contamination, curves or, bends on interface pin (OLB) of TCP.
- 2. No cracks on interface pin (OLB) of TCP
- 3. NO contamination, solder residue or solder balls on product.
- 4. The IC on the TCP may not be damaged, circuits.
- 5. The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.
- 6. The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.
- 7. Sealant on top of the ITO circuit has not hardened
- 8. Pin type must match type in specification sheet.
- 9. LCD pin loose or missing pins.
- 10. Product packaging must the same as specified on packaging specification sheet.
- 11. Product dimension and structure must conform to product specification sheet.
- 12. The appearance of Heat Seal should not admit any dirt and break.

8. RELIABILITY

Test Item	Sample Type	Test Condition	Test result determinant gist
High	Normal temperature	70±3℃;240H	the inspection of Appearance and
temperature storage	Broad temperature	80±3℃;240H	function character.
Low	Normal temperature	-20±3°C;240H	
temperature storage	Broad temperature	-30±3°C;240H	
High temperature	Normal temperature	50℃±3℃,90%±3%RH;240H	

/humidity	Broad	60°C ±3°C,90% ±3%RH;240H	
storage High	Normal	60±3°C;96H	
temperature operation	temperature Broad	70±3°C;96H	
Low	temperature Normal	0±3℃;96H	No objection of the function character;
temperature	temperature Broad		no fatal objection of
operation	temperature	-20±3℃;96H	the appearance.
High temperature	Normal temperature	40°C±3°C,90%±3%RH;96H	
/humidity operation	Broad temperature	50°C±3°C,90%±3%RH;96H	
Temperature	Normal temperature	-20±3°C,30min→70±3°C,30min;10cycle	inspect the objections appearance, function & the whole structure
Shock	Broad temperature	-30±3°C,30min 80±3,30min;10cycle	The inspection of appearance, function & the whole structure
ESD test	ALL	Discharge modality: Air discharge. Discharge voltage: $\pm 2KV/\pm 4\ KV/\pm 6K\pm 8KV/\pm 12KV/15KV$.no software error & objection in ± 2KV~±12KV,no hardware errors & objection in ± 15KV.
		Discharge modality: Contact discharge Discharge voltage: ±2KV/±4 KV/±6KV/±8KV	no software errors & objection in \pm 2KV $\sim\pm$ 12KV,no hardware errors & objection in \pm 8KV.
Bend test	ALL	Bend velocity: 60time/min; Bendtimes:50000tims	Stimulate the folder's repeat folding, no objection of display function
Vibration test	ALL	frequencyrange:10HZ~55HZ;swing:0.75mm;Z-axist direction: 60min.	the inspection of appearance, function & the whole structure

9. PRECAUTIONS FOR USING LCD MODULES

Handing Precautions

- (1) The display panel is made of glass. Do not subject it to a mechanical shock by dropping it or impact.
- (2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- (3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- (4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- (5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol
- (6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
 - Water
 - Ketone
 - Aromatic solvents
- (7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- (8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the IO cable or the backlight cable.
 - (9) Do not attempt to disassemble or process the LCD module.
 - (10) NC terminal should be open. Do not connect anything.
 - (11) If the logic circuit power is off, do not apply the input signals.
- (12) To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Be sure to ground the body when handling the LCD modules.
 - Tools required for assembling, such as soldering irons, must be properly grounded.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions.
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

Storage Precautions

When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags (avoid high temperature high humidity and low temperatures below 0 C). Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
- Terminal electrode sections.